# onsemi

## MOSFET – N-Channel, UniFET™, FRFET<sup>®</sup>

### 500 V, 45 A, 120 m $\Omega$

# FDH45N50F

#### Description

UniFET MOSFET is **onsemi**'s high voltage MOSFET family based on planar stripe and DMOS technology. This MOSFET is tailored to reduce on-state resistance, and to provide better switching performance and higher avalanche energy strength. The body diode's reverse recovery performance of UniFET FRFET MOSFET has been enhanced by lifetime control. Its  $t_{rr}$  is less than 100 nsec and the reverse dv/dt immunity is 15 V/ns while normal planar MOSFETs have over 200 nsec and 4.5 V/nsec respectively. Therefore, it can remove additional component and improve system reliability in certain applications in which the performance of MOSFET's body diode is significant. This device family is suitable for switching power converter applications such as power factor correction (PFC), flat panel display (FPD) TV power, ATX and electronic lamp ballasts.

#### Features

- $R_{DS(on)} = 105 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V}, I_D = 22.5 \text{ A}$
- Low Gate Charge (Typ. 105 nC)
- Low C<sub>rss</sub> (Typ. 62 pF)
- 100% Avalanche Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### Applications

- Lighting
- Uninterruptible Power Supply
- AC-DC Power Supply

V <sub>DS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
500 V	120 m $\Omega$ @ 10 V	45 A

# GO

N-CHANNEL MOSFET



TO-247-3LD CASE 340CK

#### MARKING DIAGRAM



#### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

#### **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		FDH45N50F-F133	Unit V	
V <sub>DSS</sub>	Drain to Source Voltage		500		
Ι <sub>D</sub>	$ \begin{array}{llllllllllllllllllllllllllllllllllll$		45 28.4	A A	
I <sub>DM</sub>	Drain Current	-Pulsed (Note 1)	180	А	
V <sub>GSS</sub>	Gate-Source Voltage		±30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		1868	mJ	
I <sub>AR</sub>	Avalanche Current (Note 1)		45	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		62.5	mJ	
dv/dt	Peak Diode Recovery dv/dt (Note 3)	Diode Recovery dv/dt (Note 3)		V/ns	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C) –Derate Above 25°C	625 5	W W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	Operating and Storage Temperature Range		°C	
ΤL	Maximum Lead Temperature for Soldering, 1/8	300	°C		

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. Repetitive Rating: Pulse width limited by maximum junction temperature. 2. L = 1.46 mH,  $I_{AS}$  = 48 A,  $V_{DD}$  = 50 V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25 °C. 3.  $I_{SD} \le 45$  A, di/dt  $\le 200$  A/µs,  $V_{DD} \le \mathbb{B}V_{DSS}$ , Starting  $T_J$  = 25 °C.

#### PACKAGE MARKING AND ORDERING INFORMATION

Device Marking	Device	Package	Package Method	Reel Size	Tape Width	Quantity
FDH45N50F-F133	FDH45N50F	TO-247-3	Tube	-	-	30 Units

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	FDH45N50F-F133	Unit
$R_{\thetaJC}$	Thermal Resistance, Junction to Case, Max.	0.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

#### ELECTRICAL CHARACTERISTICS (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Unit
OFF CHAR	ACTERISTICS	-				
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \ \mu A, \ V_{GS} = 0 \ V$	500	-	-	V
$\begin{array}{c} \Delta \text{BV}_{\text{DSS}} \\ /  \Delta \text{T}_{\text{J}} \end{array}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 µA, Referenced to 25°C	-	0.5	_	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	25	μΑ
		$V_{DS}$ = 400 V, $T_{C}$ = 125°C	-	-	250	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30$ V, $V_{DS} = 0$ V	-	-	-100	nA
ON CHARA	CTERISTICS			-		
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS}=V_{GS},\ I_{D}=250\ \mu A$	3	-	5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22.5 A	-	0.105	0.12	Ω
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, \text{ I}_{D} = 22.5 \text{ A}$	-	49	-	S
DYNAMIC C	CHARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	$V_{DS}$ = 25 V, $V_{GS}$ = 0 V, f = 1 MHz	-	5100	6630	pF
C <sub>oss</sub>	Output Capacitance		-	790	1030	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1	-	62	-	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS}$ = 400 V, $V_{GS}$ = 0 V, f = 1 MHz	-	161	-	pF
C <sub>oss</sub> eff.	Effective Output Capacitance	$V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	342	-	pF
SWITCHING	CHARACTERISTICS	•	-	-	-	-
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 250 \text{ V}, \text{ I}_{D} = 48 \text{ A},$	-	140	290	ns
t <sub>r</sub>	Turn–On Rise Time	$V_{GS} = 10 \text{ V}, \text{ R}_{G} = 25 \Omega$ (Note 4)	-	500	1010	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		_	215	440	ns

t <sub>d(off)</sub>	Turn-Off Delay Time		-	215	440	ns
t <sub>f</sub>	Turn-Off Fall Time		-	245	500	ns
Qg	Total Gate Charge	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 48 \text{ A},$	-	105	137	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V (Note 4)	-	33	-	nC
Q <sub>gd</sub>	Gate-Drain Charge		-	45	1	nC

#### DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS

۱ <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		-	-	45	А
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		-	-	180	Α
V <sub>SD</sub>	Source to Drain Diode Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{S} = 45 \text{ A}$	-	-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_S = 45 A,$	-	188	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 100 A/µs	-	0.64	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. Essentially Independent of Operating Temperature Typical Characteristics.

#### **TYPICAL CHARACTERISTICS**



#### **TYPICAL CHARACTERISTICS**













Figure 17. Resistive Switching Test Circuit & Waveforms



Figure 18. Unclamped Inductive Switching Test Circuit & Waveforms



Figure 19. Peak Diode Recovery dv/dt Test Circuit & Waveforms

UniFET is a trademark of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries.

FRFET is a registered trademark of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries.





ON Semiconductor and use trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights or others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent\_Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>